

**IN THE SPECIFICATION**

Please amend the specification as follows:

**Beginning at page 2, line 8, please add the following paragraph:**

A<sup>1</sup>  
Fig. 7 is a block diagram of an electronic system incorporating at least one electronic assembly with a carbon nanotube thermal structure according to one embodiment of the invention.

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**Beginning at page 6, line 25, please add the following paragraphs:**

A<sup>2</sup>  
FIG. 7 is a block diagram of an electronic system 70 incorporating at least one electronic assembly 72 with a thermally conductive element between a first surface of an integrated circuit die and a heat sink, in accordance with one embodiment of the invention. Electronic system 70 is merely one example of an electronic system in which the present invention can be used. In this example, electronic system 70 comprises a data processing system that includes a system bus 73 to couple the various components of the system. System bus 73 provides communications links among the various components of the electronic system 70 and can be implemented as a single bus, as a combination of busses, or in any other suitable manner.

Electronic assembly 74 is coupled to system bus 73. Electronic assembly 72 can include any circuit or combination of circuits. In one embodiment, electronic assembly 4 includes a processor 74 which can be of any type. The IC or ICs within electronic assembly 4 can perform any other type of function.

Electronic system 70 can also include an external memory 75, which in turn can include one or more memory elements suitable to the particular application.

Electronic system 70 can also include a display device 76 or any other device that permits a system user to input information into and receive information from the electronic system 70.

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